

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD33CN10N G	**Issued**	24. February 2022
MA#	MA005700023		
Package	PG-TO252-3-313	**Weight***	319.19 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.295	0.72	0.72	7192	7192
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		461	
	non noble metal	copper	7440-50-8	147.096	46.08	46.14	460848	461447
wire	non noble metal	aluminium	7429-90-5	2.796	0.88	0.88	8760	8760
encapsulation	inorganic material	zincoxide	1314-13-2	1.398	0.44		4380	
	miscellaneous	miscellaneous	-	6.990	2.19		21898	
	plastics	epoxy resin	-	20.969	6.57		65694	
	inorganic material	silicondioxide	60676-86-0	110.435	34.60	43.80	345989	437961
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11717	11717
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4450	4461
solder	non noble metal	tin	7440-31-5	0.053	0.02		166	
	noble metal	silver	7440-22-4	0.066	0.02		208	
	non noble metal	lead	7439-92-1	2.531	0.79	0.83	7928	8302
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60082	60160
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com